

Akros Silicon

Package: 20L QLMP
 Device: AS1124

MATERIAL	WEIGHT (mg)	Components	CAS Number	Composition %	Weight/Device (mg)	% wt	ppm
Adhesive Sumitomo CRM1076NS	0.8023	Silver	7440-22-4	80.00	0.641840	0.91127	9113
		Epoxy Resins	9003-36-5	10.00	0.080230	0.11391	1139
		Diluent	26447-14-3	6.00	0.048138	0.06835	683
		Dicyandiamide	461-58-5	0.50	0.004012	0.00570	57
		Hardner	620-92-8	3.50	0.028081	0.03987	399
Lead Frame QPL	26.7324	Copper	7440-50-8	97.09	25.953151	36.84784	368478
		Iron	7439-89-6	2.30	0.614845	0.87295	8729
		Lead	7439-92-1	0.01	0.001337	0.00190	19
		Silver	7440-22-4	0.40	0.106930	0.15182	1518
		Phosporous	7723-14-0	0.09	0.024059	0.03416	342
		Zinc	7440-66-6	0.12	0.032079	0.04555	455
Plating 100% matt tin	2.6321	Tin	07440-31-5	99.99	2.631837	3.73664	37366
		Lead	07439-92-1	0.005	0.000132	0.00019	2
		Copper	07440-50-8	0.003	0.000079	0.00011	1
		Antimony	07440-36-0	0.001	0.000026	0.00004	0
Gold wire	0.7871	Gold	7440-57-5	100.00	0.787100	1.11751	11175
Encapsulation Sumitomo G770HCD	35.9710	Silica Fused	60676-86-0	89.70	32.265987	45.81070	458107
		Epoxy Resin	Trade secret	5.00	1.798550	2.55355	25536
		Phenol Resin	Trade secret	5.00	1.798550	2.55355	25536
		Carbon Black	1333-86-4	0.30	0.107913	0.15321	1532
Silicon Chip	3.5084	Si (Die)	7440-21-3	100.00	3.508400	4.98117	49812
Total weight (mg)	70.4333					100.00	1000000